

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-11. (Canceled)

12. (New) A semiconductor device in which a first semiconductor element is sealed by a sealing resin, wherein the sealing resin has a cavity portion in which a second semiconductor element is stored.

13. (New) The device of claim 12 wherein the first semiconductor element and the semiconductor element are electrically connected.

14. (New) The device of claim 12 wherein connection terminals are provided in a peripheral portion of the cavity portion, and the second semiconductor element is electrically connected to the connection terminals in a face down manner.

15. (New) The device of claim 13 wherein the first semiconductor element is adapted to perform signal processing, and the second semiconductor element includes a memory portion controlled by the first semiconductor element.

16. (New) A semiconductor device comprising:
an island on which a first semiconductor element is affixed;
a plurality of leads which extend around the island and are electrically connected to the first semiconductor element;
a sealing resin which seals the first semiconductor element, the island, and the leads; and

a cavity portion provided in the sealing resin, wherein a second semiconductor element is stored in the cavity portion.

17. (New) The device of claim 16 wherein between the first semiconductor element and second semiconductor element, bridges for electrically connecting both semiconductor elements are provided.

18. (New) The device of claim 17 wherein end portions of the leads and bridges are exposed in a peripheral portion of the cavity portion, and the second semiconductor element is mounted on the end portions.

19. (New) The device of claim 16 wherein the first semiconductor element is adapted to perform signal processing, and the second semiconductor element includes a memory portion controlled by the first semiconductor element.

20. (New) A method for manufacturing a semiconductor device comprising :
sealing a first semiconductor element electrically connected to an external electrode with a sealing resin;
providing a cavity portion in the sealing resin; and
storing a second semiconductor element in the cavity portion.

21. (New) The method of claim 20 wherein the second semiconductor element is stored in the cavity portion after performing a test of the first semiconductor element.

22. (New) The method of claim 20 including:
placing the second semiconductor element on connection terminals provided in the cavity portion, and

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fixedly fitting the second semiconductor element as part of mounting the semiconductor device by a reflow.